

LNPTM LUBRICOMPTM COMPOUND OCP34E

OCL-4534 EM

DESCRIPTION

LNP LUBRICOMP OCP34E compound is based on Polyphenylene Sulfide (PPS) - linear resin containing 20% carbon fiber and 15% PTFE/silicone. Added features of this grade include: Easy Molding, Electrically Conductive, Wear Resistant.

GENERAL INFORMATION	
Features	${\it Electrically Conductive, Good Processability, Wear resistant, Carbon fiber filled, High stiffness/Strength}$
Fillers	Carbon Fiber, PTFE/Silicone
Polymer Types	Polyphenylene Sulfide, Linear (PPS, Linear)
Processing Techniques	Injection Molding

INDUSTRY	SUB INDUSTRY
Building and Construction	Building Component
Consumer	Sport/Leisure, Personal Accessory, Home Appliances, Commercial Appliance
Electrical and Electronics	Mobile Phone - Computer - Tablets
Industrial	Electrical

TYPICAL PROPERTY VALUES

Revision 20231109

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
MECHANICAL (1)			
Tensile Stress, break	164	MPa	ASTM D638
Tensile Strain, break	1.6	%	ASTM D638
Tensile Modulus, 50 mm/min	18960	MPa	ASTM D638
Flexural Stress	231	MPa	ASTM D790
Flexural Modulus	14960	MPa	ASTM D790
Tensile Stress, break	159	MPa	ISO 527
Tensile Strain, break	1.3	%	ISO 527
Tensile Modulus, 1 mm/min	16590	MPa	ISO 527
Flexural Stress	236	MPa	ISO 178
Flexural Modulus	15320	MPa	ISO 178
IMPACT (1)			
Izod Impact, unnotched, 23°C	389	J/m	ASTM D4812
Izod Impact, notched, 23°C	48	J/m	ASTM D256
Instrumented Dart Impact Energy @ peak, 23°C	4	J	ASTM D3763
Multiaxial Impact	2	J	ISO 6603
Izod Impact, unnotched 80*10*4 +23°C	28	kJ/m²	ISO 180/1U
Izod Impact, notched 80*10*4 +23°C	8	kJ/m²	ISO 180/1A
THERMAL (1)			
HDT, 1.82 MPa, 3.2mm, unannealed	265	°C	ASTM D648
HDT/Af, 1.8 MPa Flatw 80*10*4 sp=64mm	260	°C	ISO 75/Af



PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
PHYSICAL (1)			
Density	1.46	g/cm³	ASTM D792
Moisture Absorption, (23°C/50% RH/24 hrs)	0.02	%	ASTM D570
Mold Shrinkage, flow, 24 hrs ⁽²⁾	0.1	%	ASTM D955
Mold Shrinkage, xflow, 24 hrs ⁽²⁾	0.4	%	ASTM D955
Mold Shrinkage, flow, 24 hrs ⁽²⁾	0.08	%	ISO 294
Mold Shrinkage, xflow, 24 hrs ⁽²⁾	0.39	%	ISO 294
Density	1.46	g/cm³	ISO 1183
Moisture Absorption (23°C / 50% RH)	0.02	%	ISO 62
INJECTION MOLDING (3)			
Drying Temperature	120 – 150	°C	
Drying Time	4	Hrs	
Melt Temperature	315 – 320	°C	
Front - Zone 3 Temperature	330 – 345	°C	
Middle - Zone 2 Temperature	320 – 330	°C	
Rear - Zone 1 Temperature	305 – 315	°C	
Mold Temperature	140 – 165	°C	
Back Pressure	0.2 – 0.3	MPa	
Screw Speed	30 – 60	rpm	

- (1) The information stated on Technical Datasheets should be used as indicative only for material selection purposes and not be utilized as specification or used for part or tool design.
- (2) Measurements made from laboratory test coupon. Actual shrinkage may vary outside of range due to differences in processing conditions, equipment, part geometry and tool design. It is recommended that mold shrinkage studies be performed with surrogate or legacy tooling prior to cutting tools for new molded article.
- (3) Injection Molding parameters are only mentioned as general guidelines. These may not apply or may need adjustment in specific situations such as low shot sizes, large part molding, thin wall molding and gas-assist molding.

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